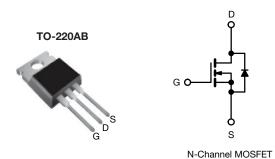
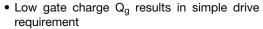


Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V)	400)
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	1.0
Q _g max. (nC)	22	
Q _{gs} (nC)	5.8	
Q _{gd} (nC)	9.3	
Configuration	Sing	le

FEATURES





Improved gate, avalanche and dynamic dV/dt ruggedness



- Fully characterized capacitance and avalanche voltage and current
- Effective C_{oss} specified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

TYPICAL SMPS TOPOLOGIES

- Single transistor flyback Xfmr. reset
- Single transistor forward Xfmr. reset (both US line input only)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF730APbF
Lead (Pb)-free and halogen-free	IRF730APbF-BE3

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	400	V
Gate-source voltage		V_{GS}	± 30	7 v	
Continuous drain current	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		5.5	
Continuous drain current	V _{GS} at 10 V	T _C = 100 °C	I _D	3.5	Α
Pulsed drain current ^a			I _{DM}	22	
Linear derating factor				0.6	W/°C
Single pulse avalanche energy b			E _{AS}	290	mJ
Repetitive avalanche current a			I _{AR}	5.5	А
Repetitive avalanche energy ^a			E _{AR}	7.4	mJ
Maximum power dissipation $T_C = 25 ^{\circ}C$ P_D 74		74	W		
Peak diode recovery dV/dt ^c			dV/dt	4.6	V/ns
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^d	For	10 s		300	7
Mounting torque	6 20 or l	6-32 or M3 screw		10	lbf ⋅ in
Mounting torque	0-32 Of 1	vio sciew		1.1	N⋅m

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting $T_J = 25$ °C, L = 19 mH, $R_g = 25 \Omega$, $I_{AS} = 5.5$ A (see fig. 12)
- c. $I_{SD} \le 5.5$ Å, $dI/dt \le 90$ Å/µs, $V_{DD} \le V_{DS}$, $T_{J} \le 150$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJC}	-	1.70	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJA}	-	62	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS}	= 0 V, I _D = 250 μA	400	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	ce to 25 °C, I _D = 1 mA	-	0.5	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.5	V
Gate-source leakage	I _{GSS}		V _{GS} = ± 30 V	1	-	± 100	nA
7		V _{DS} :	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$		-	25	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 320 \	/, V _{GS} = 0 V, T _J = 125 °C	1	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.3 A ^b	1	-	1.0	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 3.3 A	3.1	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	600	-	
Output capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$	-	103	-	1
Reverse transfer capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	4.0	-	
Output capacitance	C _{oss}		V _{DS} = 1.0 V, f = 1.0 MHz	1	890	-	- pF -
		V _{GS} = 0 V	V _{DS} = 320 V, f = 1.0 MHz	-	30	-	
Effective output capacitance	Coss eff.		V _{DS} = 0 V to 320 V ^c	1	45	-	
Total gate charge	Qg			-	-	22	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 3.5 \text{ A}, V_{DS} = 320 \text{ V}$ see fig. 6 and 13 b	-	-	5.8	nC
Gate-drain charge	Q _{gd}		See lig. 0 and 15	1	-	9.3	
Turn-on delay time	t _{d(on)}			-	10	-	ns
Rise time	t _r		$V_{DD} = 200 \text{ V}, I_D = 3.5 \text{ A}$		22	-	
Turn-off delay time	t _{d(off)}	$R_g = 12 \Omega, R_D = 57 \Omega,$ see fig. 10 b		1	20	-	
Fall time	t _f		_ see lig. 10		16	-	
Gate input resistance	Rg	f = 1 MHz, open drain		2.7	-	10.9	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.5	
Pulsed diode forward current ^a	I _{SM}			-	-	22	A
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 5.5 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T 05 %C !	0 E A -11/-14 - 400 A / - b	-	370	550	ns
Body diode reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 3.5 \text{A}, dI/dt = 100 \text{A/}\mu\text{s}^{\text{b}}$		-	1.6	2.4	μC
Forward turn-on time	t _{on}	Intrinsic to	ırn-on time is negligible (turn	on is dor	ninated b	v L _s and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

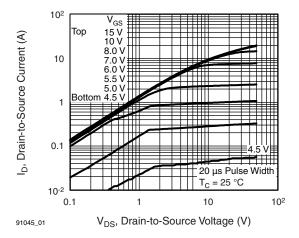


Fig. 1 - Typical Output Characteristics

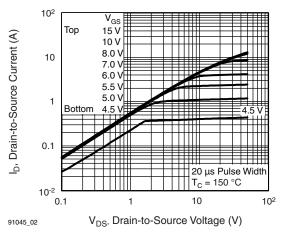


Fig. 2 - Typical Output Characteristics

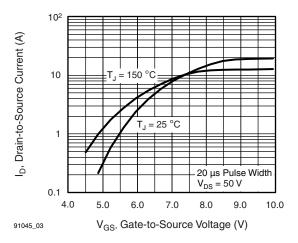


Fig. 3 - Typical Transfer Characteristics

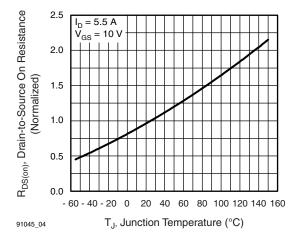


Fig. 4 - Normalized On-Resistance vs. Temperature

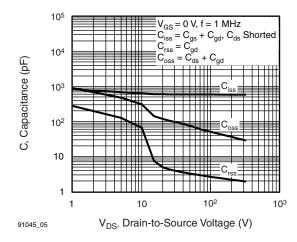


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

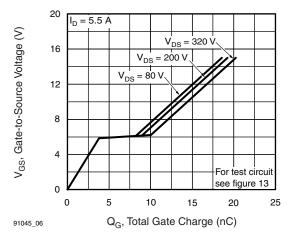


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



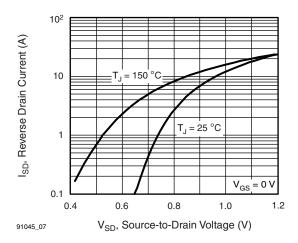


Fig. 7 - Typical Source-Drain Diode Forward Voltage

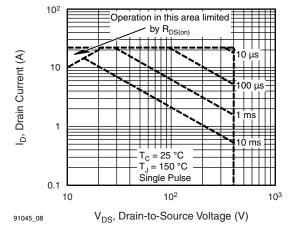


Fig. 8 - Maximum Safe Operating Area

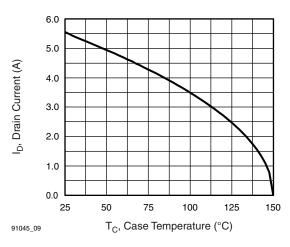


Fig. 9 - Maximum Drain Current vs. Case Temperature

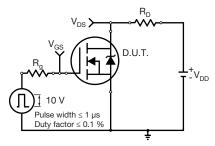


Fig. 10 - Switching Time Test Circuit

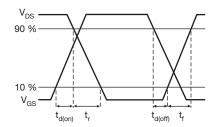


Fig. 11 - Switching Time Waveforms

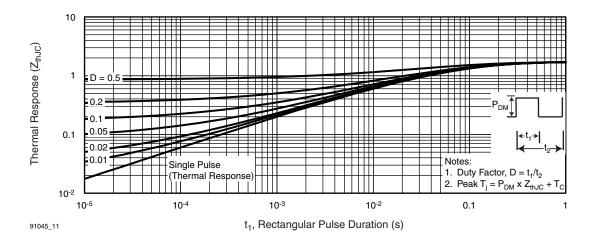




Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

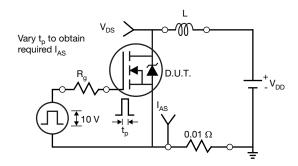


Fig. 13 - Unclamped Inductive Test Circuit

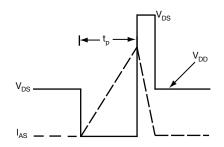


Fig. 14 - Unclamped Inductive Waveforms

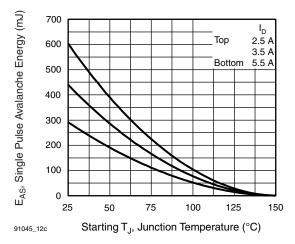


Fig. 15 - Maximum Avalanche Energy vs. Drain Current

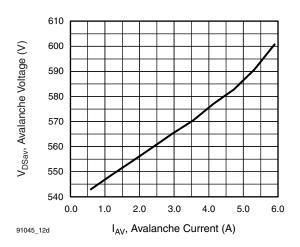


Fig. 16 - Typical Drain Source Voltage vs. Avalanche Current

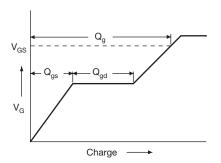


Fig. 17 - Basic Gate Charge Waveform

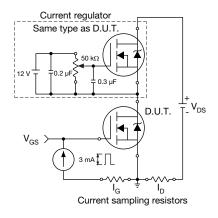
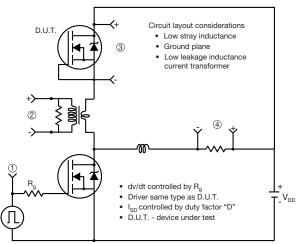


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



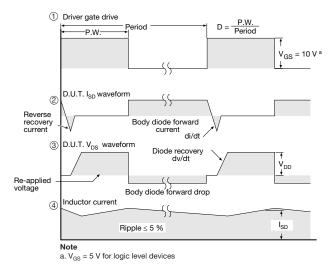


Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIM	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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